

DDTA114YLP DDTA144ELP DDTC113TLP DDTC114ELP DDTC114YLP DDTC123JLP DDTC143ZLP DDTC144ELP

Part Number: **DDTC1xx(X)LP-p**  
Weight (mg): 0.8918

p = package designator  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.88	0.0435	1000000	48778
Leadframe	C7025	Cu	7440-50-8	95.90%	36.52	0.3257	959000	350243
		Si	7440-21-3	0.73%			7250	2648
		Ni	7440-02-0	3.20%			32000	11687
		Mg	7439-95-4	0.18%			1750	639
Leadframe Plating	Nickel	Ni	7440-02-0	100.00%	0.84	0.0075	1000000	8410
	Palladium	Pd	2023568	100.00%	0.08	0.0007	1000000	785
	Gold	Au	7440-57-5	100.00%	0.01	0.0001	1000000	112
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.55	0.0138	1000000	15474
Encapsulation	EME-G770HT	Silica fused	60676-86-0	93.50%	53.61	0.4781	935000	501260
		Epoxy resin	-----	3.00%			30000	16083
		Phenol resin	-----	3.00%			30000	16083
		Carbon Black	1333-86-4	0.50%			5000	2681
Die Attach Epoxy	QMI519	Ag	7440-22-4	80.00%	2.51	0.0224	800000	20094
		palladium compound	----	0.15%			1500	38
		2,6-Di-tert-butyl-p-cresol	128-37-0	0.01%			50	1
		Hydroquinone	123-31-9	0.00%			1	0
		Acrylate	----	15.84%			158449	3980
		Bismaleimide resin	----	3.00%			30000	754
		Polymer of polybutadiene and anlydride	----	1.00%			10000	251
				<b>Total</b>	<b>100.00</b>	<b>0.8918</b>		<b>1000000</b>

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaB
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Dimethyl fumarate	Polychlorinated Naphthalenes ( > 3 chlorine atoms)
Halogens	Radioactive Substances
Hexavalent chromium compounds	Red Phosphorus
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)
REACH SVHCs and other Substances of Concern:	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Anthracene	Bis (2-ethyl(hexyl)phthalate) (DEHP)
4,4'- Diaminodiphenylmethane	Hexabromocyclododecane (HBCDD)
Dibutyl phthalate	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cyclododecane	Bis(tributyltin)oxide
Cobalt dichloride	Lead hydrogen arsenate
Diarsenic pentoxide	Triethyl arsenate

Diarsenic trioxide  
Sodium dichromate, dihydrate

Beryllium, Beryllium Alloys and Compounds  
Hydrazine  
Tetrachloroethylene  
Toluene  
Toluene Diisocyanate

Benzyl butyl phthalate

Methylene Chloride  
Trichloroethene  
Methyl Ethyl Ketone  
Xylenes